TE Internal #: 2108693-4

Preloaded - C-Clip PCB Spring Contact, Scalable, Side Protected, 1.1 mm [.043 in] Uncompressed Height, .098 in Length, 1 mm, [.039 in] Width, .87 mm

View on TE.com >



#### Connectors > Contacts > PCB Spring Contacts











Spring Finger Type: Preloaded - C-Clip

Scalable: Yes

Side Protected: Yes

Uncompressed Height: 1.1 mm [.043 in]

Product Length: [.098 in]

#### **Features**

### Product Type Features

Connector & Contact Terminates To	Printed Circuit Board
Connector System	Board-to-Board
Spring Finger Type	Preloaded - C-Clip
Scalable	Yes

## **Configuration Features**

Number of Positions	1
Side Protected	Yes

#### **Contact Features**

Contact Underplating Material	Nickel
Contact Base Material	Copper Alloy
PCB Contact Termination Area Plating Material	Gold
Contact Working Range (Low)	.65 mm[.026 in]
Contact Working Range (High)	.87 mm[.034 in]
Point of Contact Area Plating Material	Gold
Tome or correct rating waterial	3013



Contact Current Rating (Max)	.5 A
Dimensions	
Uncompressed Height	1.1 mm[.043 in]
	.098 in
Product Width	1 mm[.039 in]
Usage Conditions	
Operating Temperature Range	-40 - 85 °C[-40 - 185 °F]
Operation/Application	
Circuit Application	Signal
Packaging Features	
Packaging Method	Tape & Reel
Packaging Quantity	9000

### **Product Compliance**

For compliance documentation, visit the product page on TE.com>

EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JAN 2025 (247) Candidate List Declared Against: JUNE 2024 (241) Does not contain REACH SVHC
Halogen Content	Low Halogen - Br, Cl, F, I < 900 ppm per homogenous material. Also BFR/CFR/PVC Free
Solder Process Capability	Not reviewed for solder process capability

#### Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach



# Compatible Parts



## Customers Also Bought

















TE Part #GA10K3CG1267 CHPC-TAIWAN GOLD CHIP TE Part #2428274-3

QSFP28-QSFP28,AOC 3m,SonyVCSEL,

BER 1E-12

### **Documents**

**Product Drawings** 

1.1H SPRING FINGER WITH EMBOSS

English

**CAD Files** 

3D PDF



3D

**Customer View Model** 

ENG\_CVM\_CVM\_2108693-4\_A.2d\_dxf.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_2108693-4\_A.3d\_igs.zip

English

**Customer View Model** 

ENG\_CVM\_CVM\_2108693-4\_A.3d\_stp.zip

English

By downloading the CAD file I accept and agree to the **Terms and Conditions** of use.

**Product Specifications** 

**Product Specification** 

English